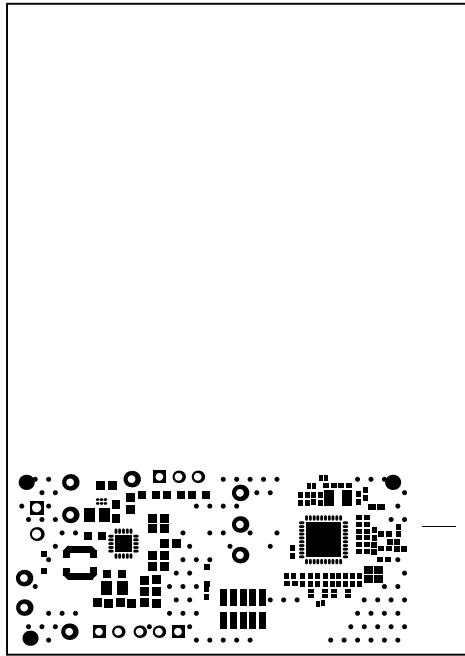
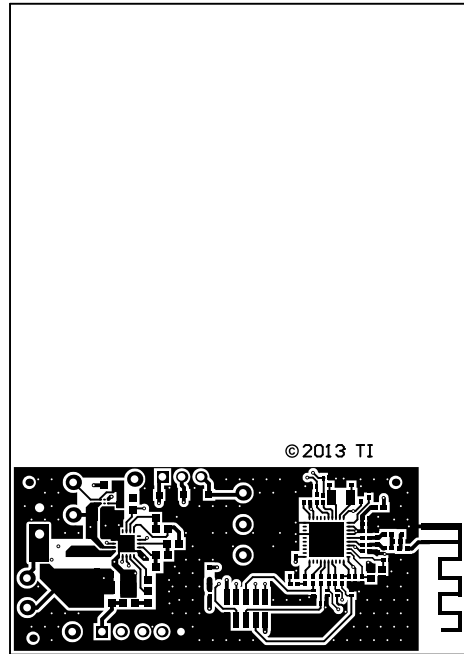


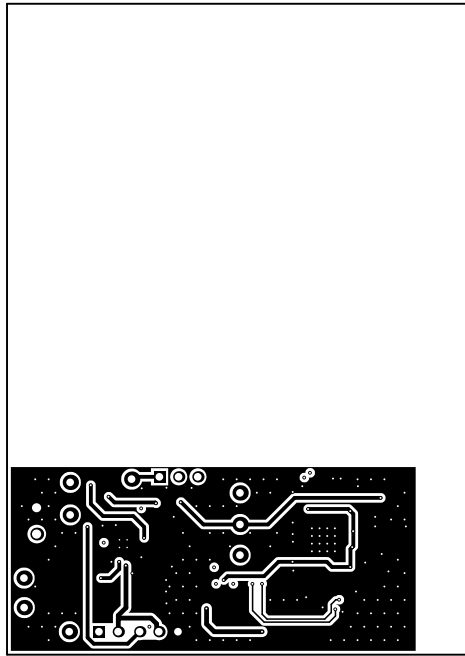
| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISE4002 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | | | |
| PLOT NAME = Top Overlay | GENERATED : 3/12/2014 10:01:50 AM | TEXAS INSTRUMENTS | |



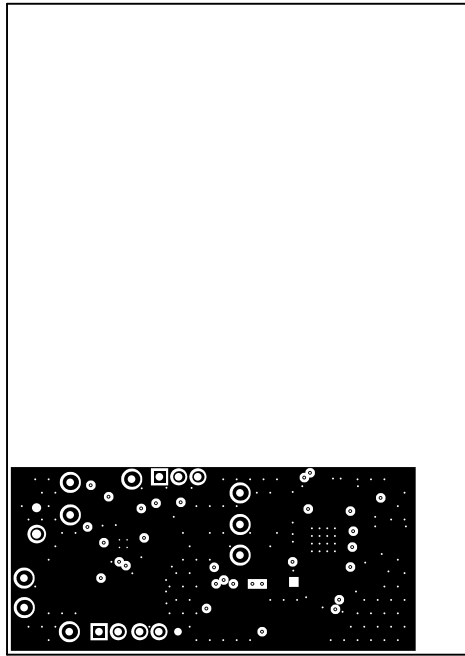
| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISE4002 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | | | |
| PLOT NAME = Top Solder Mask | GENERATED : 3/12/2014 10:01:50 AM | TEXAS INSTRUMENTS | |



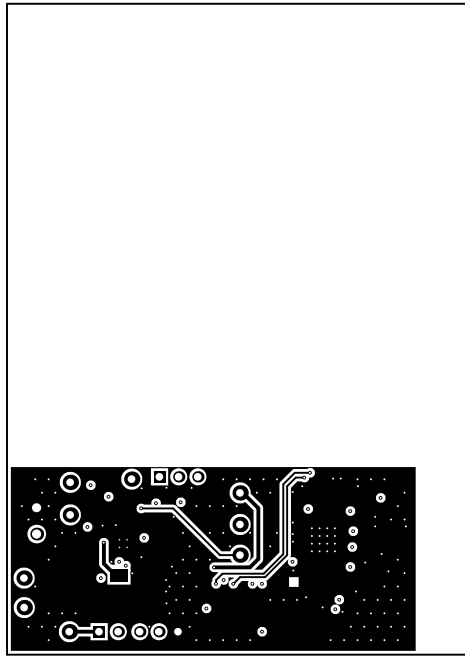
| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISE4002 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer | | | |
| PLOT NAME = Top Layer | GENERATED : 3/12/2014 10:01:50 AM | TEXAS INSTRUMENTS | |



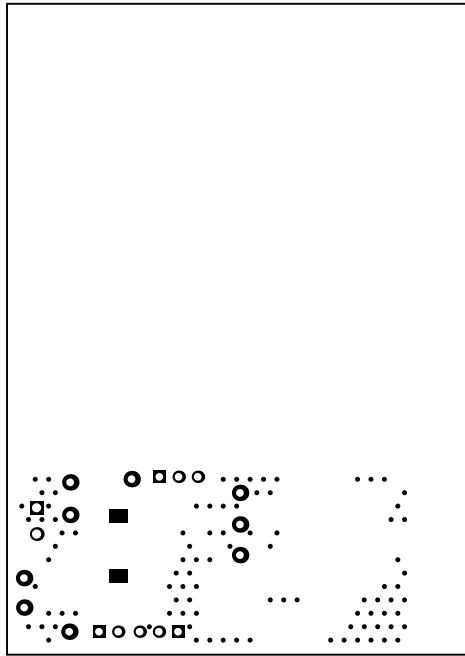
| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISE4002 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = MidBeqed2outline | | | |
| PLOT NAME = Midlayer2 | GENERATED : 3/12/2014 10:01:51 AM | TEXAS INSTRUMENTS | |



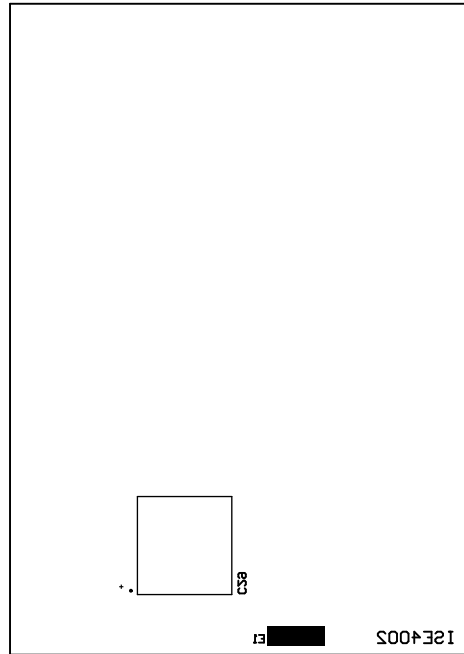
| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISE4002 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = MidBegeed1Outline | | | |
| PLOT NAME = Midlayer1 | GENERATED : 3/12/2014 10:01:51 AM | TEXAS INSTRUMENTS | |



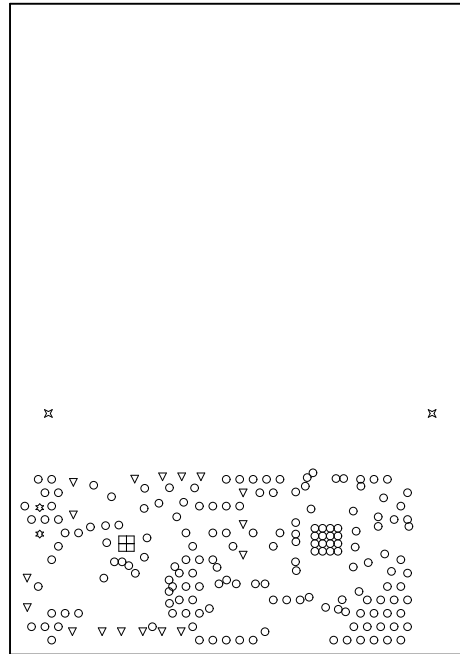
| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISE4002 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | | | |
| PLOT NAME = Bottom Layer | GENERATED : 3/12/2014 10:01:51 AM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISE4002 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 3/12/2014 10:01:51 AM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISE4002 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | | | |
| PLOT NAME = Bottom Overlay | GENERATED : 3/12/2014 10:01:51 AM | TEXAS INSTRUMENTS | |

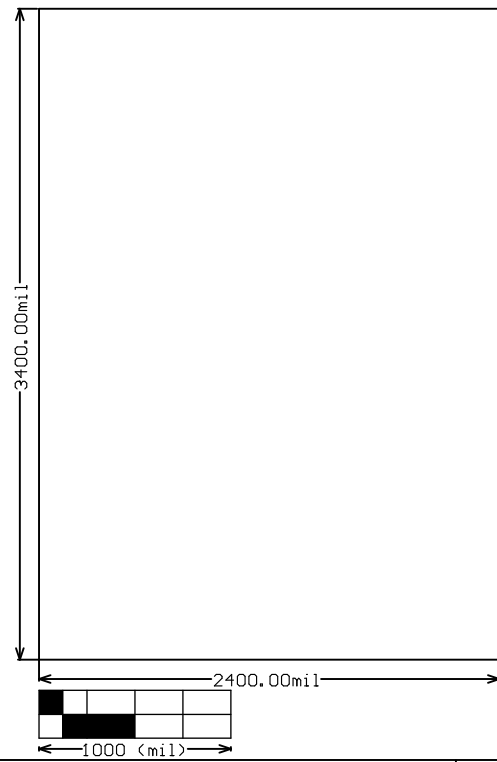


| Symbol | Hit Count | Tool Size | Physical Length | Rout Path Length | Plated | Hole Type |
|-----------|-----------|-------------------|-----------------|------------------|--------|-----------|
| □ | 4 | 7.874mil (0.2mm) | | | PTH | Round |
| ○ | 171 | 10mil (0.254mm) | | | PTH | Round |
| ▽ | 17 | 40mil (1.016mm) | | | PTH | Round |
| ☆ | 2 | 47.244mil (1.2mm) | | | PTH | Round |
| ⊠ | 2 | 125mil (3.175mm) | 200mil (5.08mm) | 75mil (1.905mm) | PTH | Slot |
| 196 Total | | | | | | |

Slot definitions : Rout Path Length = Calculated from tool start centre position to tool end centre position.
 Physical Length = Rout Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Table

| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISE4002 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | | | |
| PLOT NAME = Drill Drawing | GENERATED : 3/12/2014 10:01:51 AM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISE4002 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | | | |
| PLOT NAME = Board Dimensions | GENERATED : 3/12/2014 10:01:52 AM | TEXAS INSTRUMENTS | |

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